20th anniversary!

## Call for Papers

# ICEP 2021

## 2021 International Conference on Electronics Packaging

**Date:** May 12 ~ 15, 2021
**Venue:** Miraikan (National Museum of Emerging Science and Innovation), Tokyo, Japan
**Style:** **On-site & On-line Hybrid Conference**
Please note: The conference style may be changed to Full On-Line depending on the future restrictions on travel
**Sponsor:** Japan Institute of Electronics Packaging (JIEP)
**Technical Co-Sponsors:** IEEE EPS Japan Chapter, iMAPS

## Conference Topics & Special Notice for Authors

### Topic Category 1 (tentative)

Detail of category is **TBD**, may be modified.

- Advanced Packaging
- Quality, Modeling, and Reliability

### Topic Category 2 (tentative)

Detail of category is **TBD**, may be modified.

- Interconnections
- Materials and Processing

### Topic Category 3 (tentative)

Detail of category is **TBD**, may be modified.

- Optelectronics
- Power Electronics
- Highspeed, Wireless and Components
- Emerging technologies

### Oral Presentation

☐ At the abstract submission, the authors will be asked to choose their preference from: a) **On-site live session** at Miraikan, or b) **On-demand session (video streaming presentation)**, when their abstracts are accepted for the oral presentations.

☐ **ALL** the on-line presenters will be required to prepare the pre-recorded videos of their presentations for backup **ONLY** when something wrong happens on the streaming.

### Poster Presentation

☐ The posters will be exhibited **ON-LINE**.

☐ All the authors will be asked to give **on-line short presentations** in the poster session.

☐ Live discussion opportunities will be provided for poster presenters (TBD).

- From the standpoint of being an international non-commercial conference where the public interests are secured, ICEP committee kindly require **NOT** to record the presentations and discussions in any way, including screen capturing.
- The authors are required to release the copyright of all the submitted contents. For details, visit: https://ux.nu/o27ui

ICEP 2021 International Conference on Electronics Packaging

See the backside for details

JIEP IEEE EPS IEEE ELECTRONICS PACKAGING SOCIETY iMAPS

## Important Dates

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| **Abstract submission open:** | **September 1st, 2020** |
| **Abstract deadline:** | **November 30th, 2020** |
| **Notification of acceptance:** | **January 15th, 2021** |
| **Final manuscript deadline:** | **March 1st, 2021** |

- Authors are encouraged to use the abstract template found at the conference website: http://www.jiep.or.jp/icep/
- Once the abstract is accepted, the author will be required to prepare a **2-pages final paper**: For the final paper format, see: http://www.jiep.or.jp/icep/
- Accepted and presented papers will be published in the conference proceedings and submitted to IEEE Xplore as well as other Abstracting and Indexing (A&I) databases (EI Compendex and INSPEC).
- Authors are encouraged to submit their manuscripts to Transactions of The Japan Institute of Electronics Packaging, with enhanced contents of 4 – 10 pages. For details, please see: https://www.jstage.jst.go.jp/browse/jiepeng/-char/en

## Outstanding Technical Paper Award

This award recognizes the outstanding papers presented at ICEP. The award will be given to the presenting author and co-authors of the selected papers.

**Funding**: The award is sponsored by JIEP.
**Eligibility**: The presenter must be listed as one of the authors. Conference papers must be submitted on or before the due date.
**Basis**: Papers are reviewed based on: Originality, technical contents, relevance, technical impact of the written paper, and the quality of the conference presentation.

## IEEE EPS Japan Chapter Young Award

This award recognizes the excellent papers presented by young scientists and engineers at ICEP. This award will be given to the presenting author.

**Funding**: The award is sponsored by IEEE EPS Japan Chapter.
**Eligibility**: The presenter must be listed as the first author of their paper. The presenter must be younger than 35 years old on December 31 of the presentation year. Previous winners are not eligible. Conference papers must be submitted on or before the due date. The award recipient must be a member of IEEE and EPS at the time the award is received.
**Basis**: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

## JIEP Poster Award

This award recognizes the excellent poster work. The award will be given to the presenting author and co-authors.

**Funding**: The award is sponsored by JIEP.
**Eligibility**: The presenter must be listed as one of their paper's authors. Conference papers must be submitted on or before the due date.
**Basis**: The basis is same as Outstanding Technical Paper Award, with different allocation of points on each item.

## About ICEP

ICEP is counted as one of the largest Asian international conferences on electronic packaging, attracting more than 400 attendees and hosting over 30 technical sessions every year since 2001. This time, ICEP2021, is the 20th anniversary, being held at Miraikan, Tokyo, Japan, where the attendees will feel an “electric” atmosphere of the Olympic games.

Unfortunately, we had to cancel the last time ICEP due to worldwide COVID-19 situation. However, regarded this experience as a good opportunity to increase the choices of participation measures, ICEP 2021 will take place in an on-site/on-line hybrid system so that global participants can keep joining cutting-edge discussions.

We sincerely hope all the attendees make the most of ICEP 2021 as a cross-cutting platform to dynamize and deepen their R&D activities.

**Main Sponsor**: Japan Institute for Electronics Packaging (JIEP)
**Technical Co-Sponsors**: IEEE Electronics Packaging Society (EPS) Japan Chapter, IMAPS

## Registration Fee

The details of the registration fee will be announced in the conference HP ASAP when the conference type is finally decided (no later than **January 2021)**.

The following items are included in the registration fee: Receptions, proceedings, and **the archive of all 1st to 19th ICEP proceedings as the privilege of the 20th anniversary**. How-to-get will be announced in the homepage, too.

## Organizing Committee

**General Chair:**
Eiji Higurashi, National Institute of Advanced Industrial Science and Technology (AIST)

**General Vice Chairs:**
Shigenori Aoki, LINTEC corporation
Katsuyuki Miyama, Hokkaido University of Science
Akitsu Shigetou, National Institute for Materials Science (NIMS)

## Sponsorship Opportunities

The ICEP committee intends to provide cross-disciplinary support for R&D related to electronics packaging technology and is broadly recruiting sponsors who kindly support this idea. Sponsors will receive various benefits in addition to discounted fees. The detail will be announced on the conference website soon.

## Contact

ICEP 2021 secretariat (The Japan Institute of Electronics Packaging)
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E-mail: icep2021@jiep.or.jp
URL: http://www.jiep.or.jp/icep/